

International Application No.: PCT/JP2004/007175
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IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

ABSTRACT OF THE DISCLOSURE

An electronic component having thermal shock resistance and high reliability includes an element having a functional part and a first frame-shaped electrode surrounding the functional part, a substrate including a second frame-shaped electrode, and a solder sealing frame provided on the surface of at least one of the first frame-shaped electrode and the second frame-shaped electrode. In the electronic component device, the element and the substrate are bonded with the solder sealing frame, and the functional part provided on the element is hermetically sealed in a space formed between the element and the substrate. When the difference in expansion in the x direction between the element and the substrate is represented by Q_x and the difference in expansion in the y direction between the element and the substrate is represented by Q_y , then in each of the first frame-shaped electrode, the second frame-shaped electrode, and the solder sealing frame, a width of a strip-shaped portion extending in the direction having the larger difference in expansion is smaller than a width of a strip-shaped portion extending in the direction having the smaller difference in expansion.